

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
	4	3.500mm (137.79mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
0	840	0.500mm (19.69mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
$\nabla$	900	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	1744 Total						

	LAYER BUILD DATA							
SHT	DESCRIPTION	PLOTFILE	EXT	P/N				
1	CUTTING & DRILLING DRAWING	SMP [Panel]	GD1	-				
2	TOP SIDE LEGEND	SMP [Panel]	GTO	POS				
3	TOP SIDE SOLDER MASK	SMP [Panel]	GTS	NEG				
4	TOP SIDE	SMP [Panel]	GTL	POS				
5	BOTTOM SIDE	SMP [Panel]	GBL	POS				
6	BOTTOM SIDE SOLDER MASK	SMP [Panel]	GBS	NEG				
7	BOTTOM SIDE LEGEND	SMP [Panel]	GBO	POS				

SOLDER STENCIL DATA						
SHT	DESCRIPTION	PLOTFILE	EXT	P/N		
1	TOP SIDE SOLDER STENCIL	SMP [Panel]	GTP	POS		
2	BOTTOM SIDE SOLDER STENCIL	SMP [Panel]	GBP	POS		

MATERIAL					
ITEM	FINAL THICKNESS	MATERIAL			
Cu	35um (ON ALL LAYERS)	COPPER CLAD			
РСВ	1.60mm	NEMA FR4			

FINISH				
ITEM	DESCRIPTION			
PCB	IMMERSION GOLD			
SOLDER MASK	BLUE PHOTO-IMAGEABLE			
LEGEND	WHITE EPOXY			

ELEC	NTIC TRONIC	S , `
TOLERANC	ES UNLESS OTHER	WISE STATED
1 = +/-0.2	1.0 = +/-0.1	1.00 = +/-0.05

UNITS							TITLE
METRIC							SN
SCALE							(CU
N/A							
	EDM	-	-	07/10/2024	01	-	DWG NUME
	DRAWN	CHECKED	APPROVED	DATE	DOC REV.	ECR NO.	SOURCE

SMP PCB
(CUTTING & DRILLING DRAWING)

(COTTIN	G & DRILLING DRAWING)		
OWG NUMBER	-	PCB VER	SHEET NO
SOURCE	SMP [Panel].PcbDoc	10.00	SHEET 1 OF























